

NDP6020P-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY		
V _{DS}	-30	V
R _{DS(on)} V _{GS} = 10 V	8	mΩ
$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}$	11	mΩ
I _D	-70	Α
Configuration	Single	

FEATURES

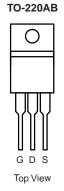
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

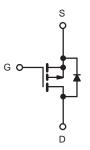


RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





P-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		- 70	
Continuous Prain Current (T. – 150 °C)	T _C = 70 °C	1 , [- 55	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	- 55	
	T _A = 70 °C	1	-45	_
Pulsed Drain Current		I _{DM}	- 200	A
Continuous Source-Drain Diode Current	T _C = 25 °C	1	- 50	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S -	- 50	
valanche Current		I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
Maximum Power Dissipation	T _C = 25 °C		50	
	T _C = 70 °C		32	\Box w
	T _A = 25 °C	P _D	7 ^{a, b}	VV
	T _A = 70 °C		5 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	5/88

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
	_	V _{GS} = - 10 V, I _D = - 10 A	8			mΩ	
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	V _{GS} = - 4.5 V, I _D = - 8 A		11		11152	
Forward Transconductancea	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b	-					<u>l</u>	
Input Capacitance	C _{iss}			3950			
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		455		pF	
Reverse Transfer Capacitance	C _{rss}	1		390			
Total Gate Charge		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		57	86	1	
	Q _g V _{DS} = 13 V, V _{GS} = 10 V, I _D = 10 A		29.5	45			
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		nC	
Gate-Drain Charge	Q _{gd}			22			
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		40	70		
Fall Time	t _f	j		9	18		
Turn-On Delay Time	t _{d(on)}			48	80	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_{q} = 1 \Omega$		34	60		
Fall Time	t _f	j		19	35		
Drain-Source Body Diode Characteris	stics					ı	
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1		
Pulse Diode Forward Current	I _{SM}				- 60	Α	
Body Diode Voltage	V _{SD}	I _S = -3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	5 55		27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1		16	27	nC	
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12			
Reverse Recovery Rise Time	t _b	†		15		ns	

Notes:

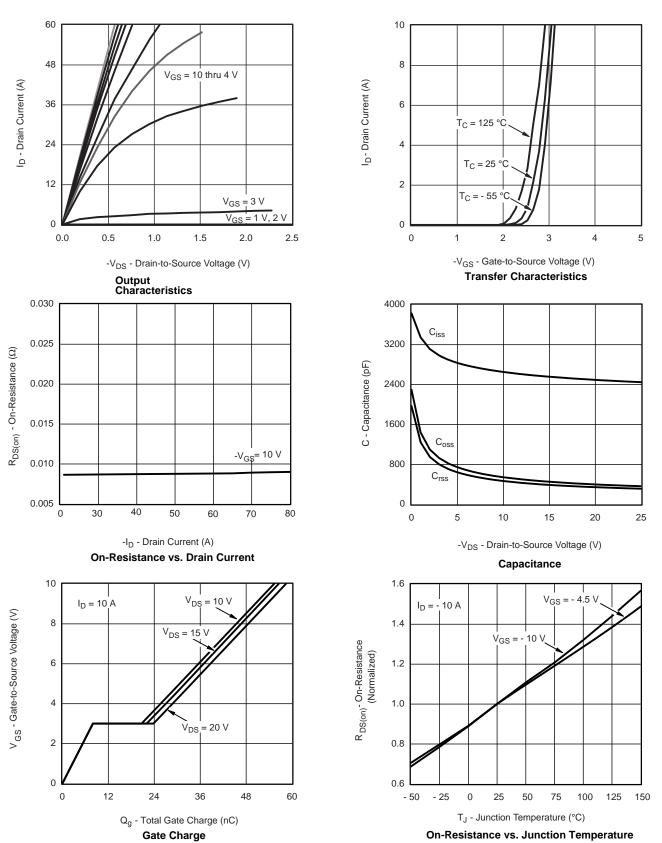
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

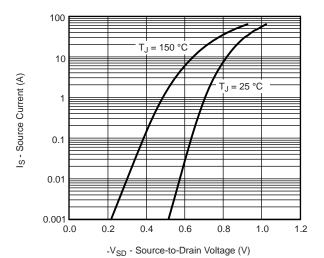


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

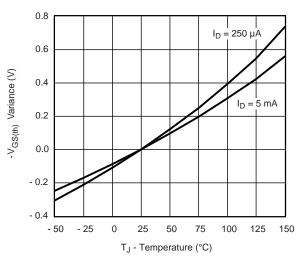




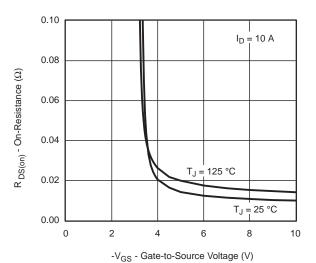
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



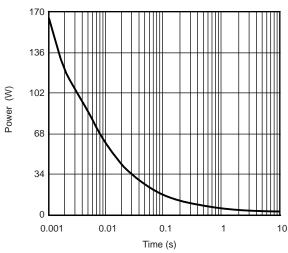
Source-Drain Diode Forward Voltage



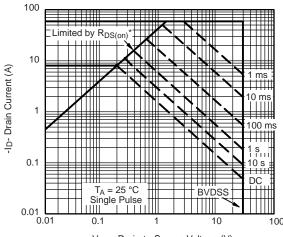
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



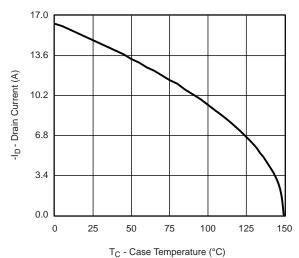
-V_{DS} - Drain-to-Source Voltage (V)

Safe Operating Area

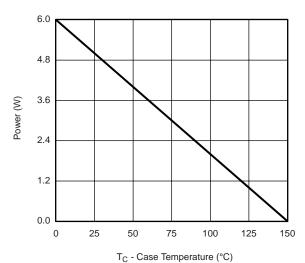
^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



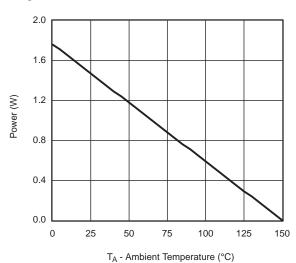
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



Power, Junction-to-Foot

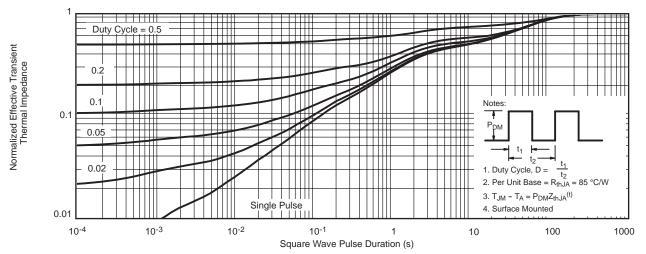


Power Derating, Junction-to-Ambient

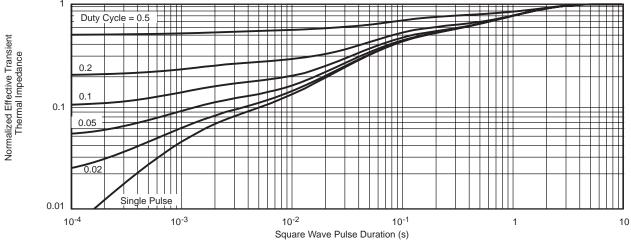
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



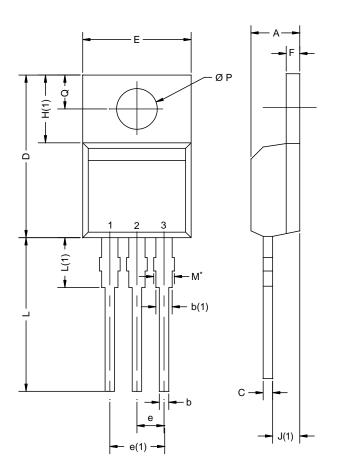
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-220AB



•	MILLIN	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØР	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	

DWG: 5471

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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